

LNPTM THERMOTUFTM COMPOUND WF0021

WF-1002 HI

DESCRIPTION

LNP THERMOTUF WF002I compound is based on Polybutylene Terephthalate (PBT) resin containing 10% glass fiber. Added features of this grade include: Impact Modified.

GENERAL INFORMATION	
Features	Impact resistant, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polybutylene Terephthalate (PBT)
Processing Techniques	Injection Molding
Regional Availability	Europe, Asia, Americas

TYPICAL PROPERTY VALUES

PROPERTIES TYPICAL VALUES UNITS **TEST METHODS** MECHANICAL⁽¹⁾ Tensile Stress, yld, Type I, 5 mm/min 64 MPa ASTM D638 55 ASTM D638 Tensile Stress, brk, Type I, 5 mm/min MPa Tensile Strain, yld, Type I, 5 mm/min 3.4 % ASTM D638 Tensile Strain, brk, Type I, 5 mm/min 4.4 % ASTM D638 Tensile Modulus, 5 mm/min 3770 MPa ASTM D638 Flexural Stress, yld, 1.3 mm/min, 50 mm span 102 MPa ASTM D790 Flexural Modulus, 1.3 mm/min, 50 mm span 3320 MPa ASTM D790 62 Tensile Stress, yield, 5 mm/min MPa 150 527 Tensile Stress, break, 5 mm/min 60 MPa ISO 527 Tensile Strain, yield, 5 mm/min 3.4 % ISO 527 Tensile Strain, break, 5 mm/min 4.3 % ISO 527 Tensile Modulus, 1 mm/min ISO 527 3670 MPa Flexural Stress 102 MPa ISO 178 Flexural Modulus, 2 mm/min ISO 178 3270 MPa IMPACT (1) 708 ASTM D4812 Izod Impact, unnotched, 23°C J/m Izod Impact, notched, 23°C 125 ASTM D256 J/m Multiaxial Impact 1 ISO 6603 Instrumented Dart Impact Total Energy, 23°C 6 Ī ASTM D3763 Izod Impact, unnotched 80*10*4 +23°C 39 kJ/m² ISO 180/1U Izod Impact, notched 80*10*4 +23°C 11 kJ/m² ISO 180/1A THERMAL⁽¹⁾ HDT, 0.45 MPa, 3.2 mm, unannealed 214 °C ASTM D648 HDT, 1.82 MPa, 3.2mm, unannealed 178 °C ASTM D648 CTE, -30°C to 30°C, flow 7.2E-05 1/°C ASTM D696 CTE, -30°C to 30°C, xflow 1.11E-04 1/°C ASTM D696

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CHEMISTRY THAT MATTERS

Revision 20241104



PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	207	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	161	°C	ISO 75/Af
PHYSICAL ⁽¹⁾			
Specific Gravity	1.32	-	ASTM D792
Density	1.32	g/cm ³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.07	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	1 – 1.5	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	1.4 – 1.8	%	ASTM D955
Moisture Absorption (23°C / 50% RH)	0.1	%	ISO 62
INJECTION MOLDING (3)			
Drying Temperature	120	°C	
Drying Time	4	Hrs	
Maximum Moisture Content	0.05	%	
Melt Temperature	240 – 265	°C	
Front - Zone 3 Temperature	260 – 270	°C	
Middle - Zone 2 Temperature	245 – 255	°C	
Rear - Zone 1 Temperature	220 – 230	°C	
Mold Temperature	80 – 100	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 - 60	rpm	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.

(3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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